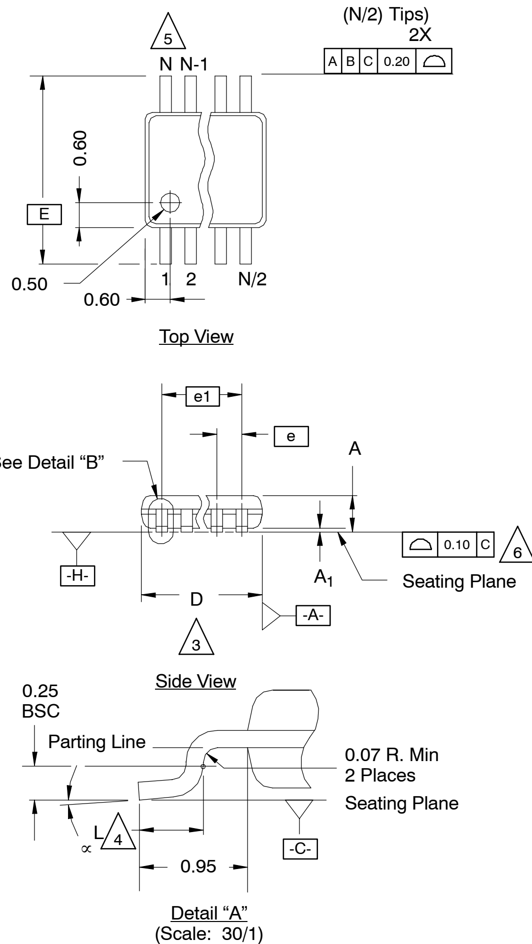
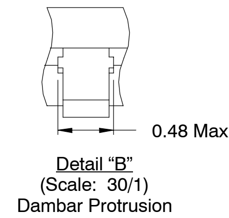
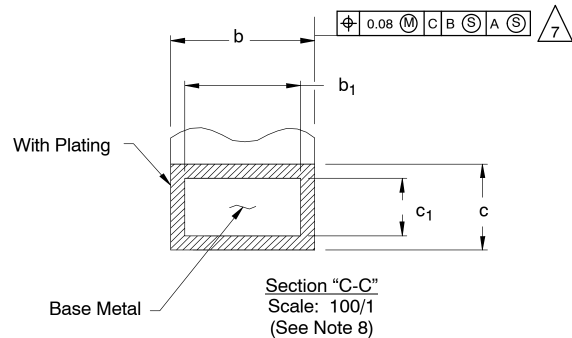
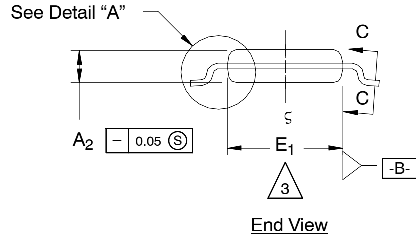
MSOP: 10-LEADS (POWER IC ONLY)

JEDEC Part Number: MO-187, (Variation AA and BA)









NOTES:

1. Die thickness allowable is 0.203 ± 0.0127.
2. Dimensioning and tolerances per ANSI.Y14.5M-1994.
3. Dimensions "D" and "E_1" do not include mold flash or protrusions, and are measured at Datum plane -H- , mold flash or protrusions shall not exceed 0.15 mm per side.
4. Dimension is the length of terminal for soldering to a substrate.
5. Terminal positions are shown for reference only.
6. Formed leads shall be planar with respect to one another within 0.10 mm at seating plane.
7. The lead width dimension does not include Dambar protrusion. Allowable Dambar protrusion shall be 0.08 mm total in excess of the lead width dimension at maximum material condition. Dambar cannot be located on the lower radius or the lead foot. Minimum space between protrusions and an adjacent lead to be 0.14 mm. See detail "B" and Section "C-C".
8. Section "C-C" to be determined at 0.10 mm to 0.25 mm from the lead tip.
9. Controlling dimension: millimeters.
10. This part is compliant with JEDEC registration MO-187, variation AA and BA.
11. Datums -A- and -B- to be determined Datum plane -H- .
12. Exposed pad area in bottom side is the same as teh leadframe pad size.

N = 10L

Dim	MILLIMETERS			Note
	Min	Nom	Max	
A	–	–	1.10	
A_1	0.05	0.10	0.15	
A_2	0.75	0.85	0.95	
b	0.17	–	0.27	8
b_1	0.17	0.20	0.23	8
c	0.13	–	0.23	
c_1	0.13	0.15	0.18	
D		3.00 BSC		3
E		4.90 BSC		
E_1	2.90	3.00	3.10	3
e		0.50 BSC		
e_1		2.00 BSC		
L	0.40	0.55	0.70	4
N		10		5
∝	0°	4°	6°	

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